



## 60V N-Channel Trench Power MOSFET

### General Description

The SJD60N100 uses advanced trench technology to provide excellent  $R_{DS(ON)}$ , low gate charge and operation with gate voltages as low as 4.5V. This device is suitable for use as a wide variety of applications.

### Features

- Low Gate Charge
- 100% UIS Tested, 100% DVDS Tested
- High Power and current handling capability
- Lead free product is acquired

### Application

- DC/DC Converter
- Ideal for high-frequency switching and synchronous rectification

### Key Performance Parameters

Parameter	Value	Unit
$V_{DS}$	60	V
$R_{DS(ON\_TYP)}$	8.9	m $\Omega$
$I_D$	50	A
$Q_G$	47.5	nC



### Package Marking and Ordering Information

Device/Ordering Code	Marking	Package	Packing	Reel Size	Tape width	Quantity
SJD60N100	SJD60N100	TO-252	Tape	\	\	2500 Pcs

**Table 1. Absolute Maximum Ratings ( $T_C=25^\circ\text{C}$  unless otherwise noted)**

Symbol	Parameter	Limit	Unit
$V_{DS}$	Drain-Source Voltage ( $V_{GS}=0V$ )	60	V
$V_{GS}$	Gate-Source Voltage ( $V_{DS}=0V$ )	$\pm 20$	V
$I_D$	Drain Current-Continuous( $T_C=25^\circ\text{C}$ )	50	A
	Drain Current-Continuous( $T_C=100^\circ\text{C}$ )	31	A
$I_{DM}$ (pluse)	Drain Current-Continuous@ Current-Pulsed (Note 1)	200	A
$P_D$	Maximum Power Dissipation( $T_C=25^\circ\text{C}$ )	57	W
	Maximum Power Dissipation( $T_C=100^\circ\text{C}$ )	23	W
$E_{AS}$	Avalanche energy (Note 2)	169	mJ
$T_J, T_{STG}$	Operating Junction and Storage Temperature Range	-55 To 150	$^\circ\text{C}$

**Table 2. Thermal Characteristic**

Symbol	Parameter	Typ	Max	Unit
$R_{JC}$	Thermal Resistance, Junction-to-Case		2.2	$^\circ\text{C}/\text{W}$



60V N-Channel Trench Power MOSFET

Table 3. Electrical Characteristics ( $T_J=25^\circ\text{C}$  unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
<b>On/Off States</b>						
$BV_{DSS}$	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=250\mu A$	60			V
$I_{DSS}$	Zero Gate Voltage Drain Current	$V_{DS}=60V, V_{GS}=0V, T_J=25^\circ\text{C}$			1	$\mu A$
		$V_{DS}=60V, V_{GS}=0V, T_J=125^\circ\text{C}$			500	nA
$I_{GSS}$	Gate-Body Leakage Current	$V_{GS}=\pm 20V, V_{DS}=0V$			$\pm 100$	nA
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_D=250\mu A$	1		2.5	V
$g_{FS}$	Forward Transconductance	$V_{DS}=5V, I_D=20A$		35		S
$R_{DS(ON)}$	Drain-Source On-State Resistance	$V_{GS}=10V, I_D=20A, T_J=25^\circ\text{C}$		8.9	10.8	$m\Omega$
$R_{DS(ON)}$	Drain-Source On-State Resistance	$V_{GS}=4.5V, I_D=15A, T_J=25^\circ\text{C}$		10.9	14.5	$m\Omega$
<b>Dynamic Characteristics</b>						
$C_{iss}$	Input Capacitance	$V_{DS}=30V, V_{GS}=0V, f=1.0\text{MHz}$		2411		pF
$C_{oss}$	Output Capacitance			124		pF
$C_{rss}$	Reverse Transfer Capacitance			116		pF
$R_g$	Gate resistance	$V_{GS}=0V, V_{DS}=0V, f=1.0\text{MHz}$		1.4		$\Omega$
<b>Switching Parameters</b>						
$t_{d(on)}$	Turn-on Delay Time	$V_{GS}=10V, V_{DS}=30V, R_L=1.5\Omega, R_{GEN}=6\Omega$		4.3		nS
$t_r$	Turn-on Rise Time			16		nS
$t_{d(off)}$	Turn-Off Delay Time			6.5		nS
$t_f$	Turn-Off Fall Time			24		nS
$Q_g$	Total Gate Charge	$V_{GS}=10V, V_{DS}=30V, I_D=20A$		47.5		nC
$Q_{gs}$	Gate-Source Charge			14.5		nC
$Q_{gd}$	Gate-Drain Charge			12.7		nC
<b>Source-Drain Diode Characteristics</b>						
$I_{SD}$	Source-Drain Current (Body Diode)				50	A
$V_{SD}$	Forward on Voltage (Note 3)	$V_{GS}=0V, I_S=20A$			0.99	V
$t_{rr}$	Reverse Recovery Time	$I_F=20A, dI/dt=100A/s$		24		ns
$Q_{rr}$	Reverse Recovery Charge	$I_F=20A, dI/dt=100A/s$		9.3		nC

Notes 1.Repetitive Rating: Pulse width limited by maximum junction temperature.

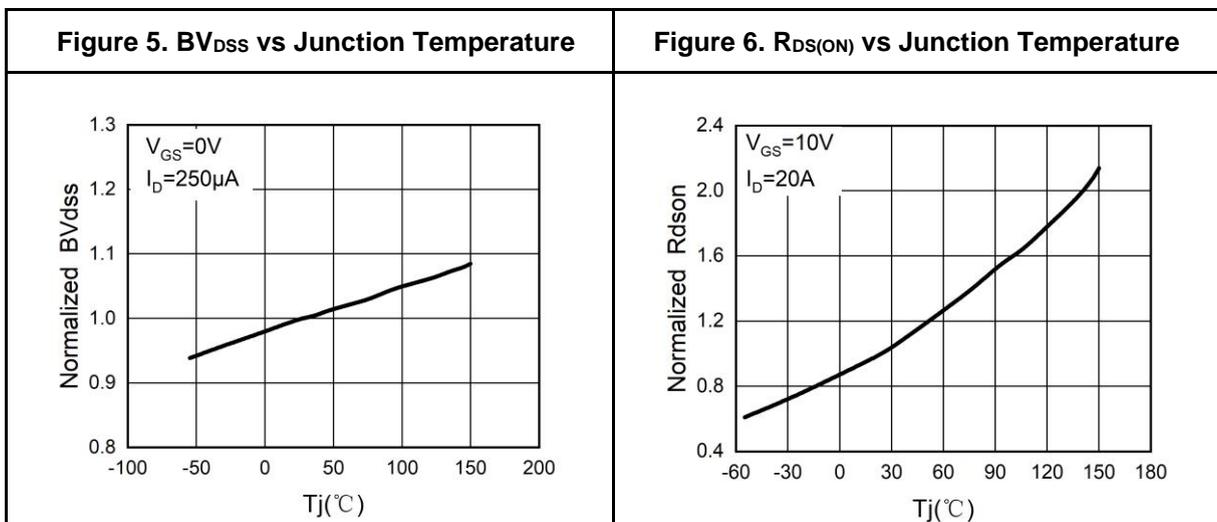
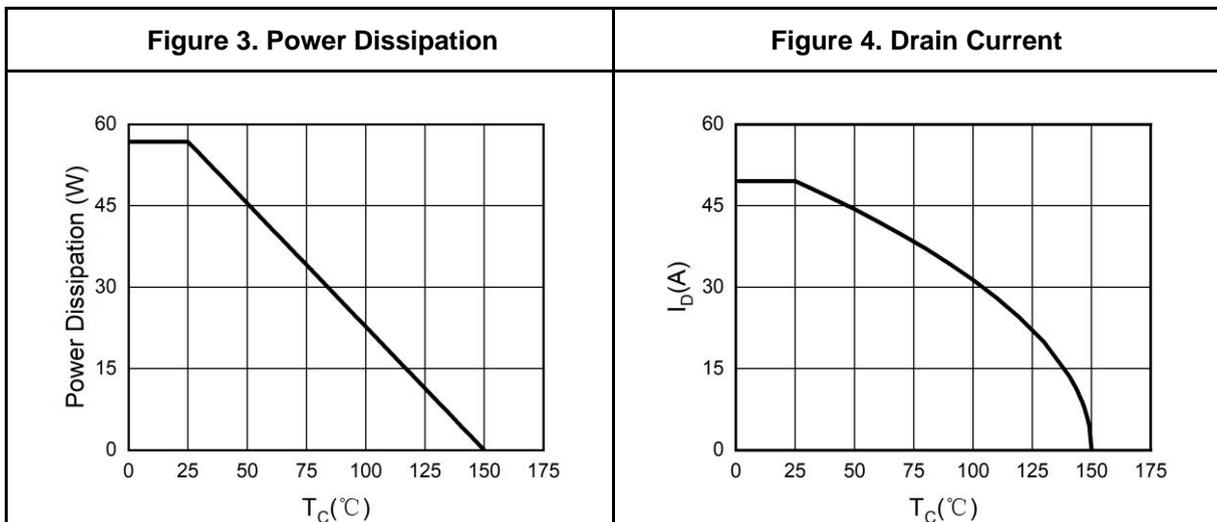
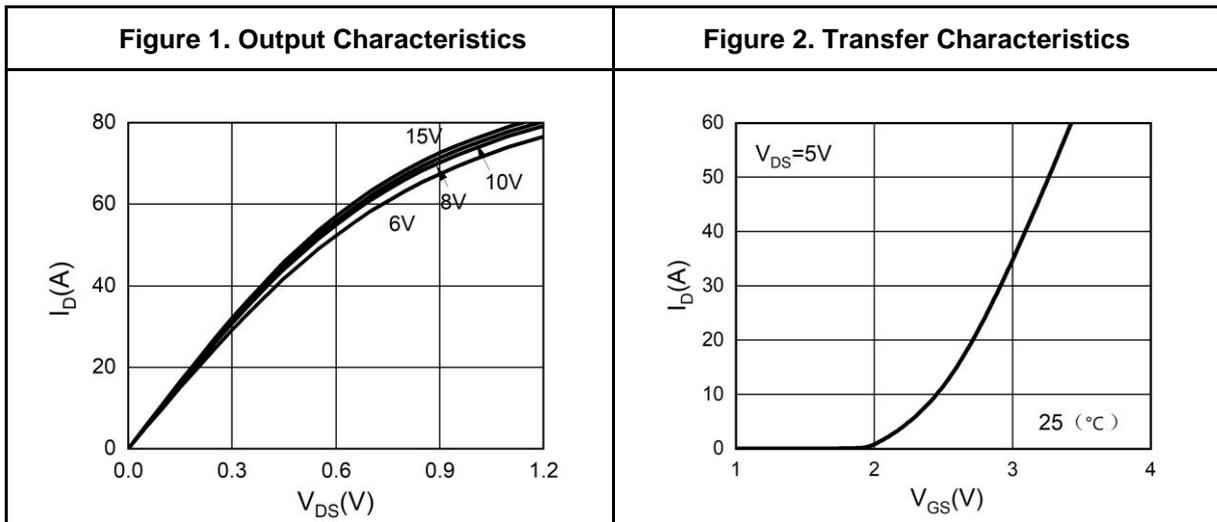
Notes 2.EAS condition:  $T_J=25^\circ\text{C}, V_{DD}=40V, V_G=10V, R_g=25\Omega, L=0.5\text{mH}$ .

Notes 3.Repetitive Rating: Pulse width limited by maximum junction temperature.



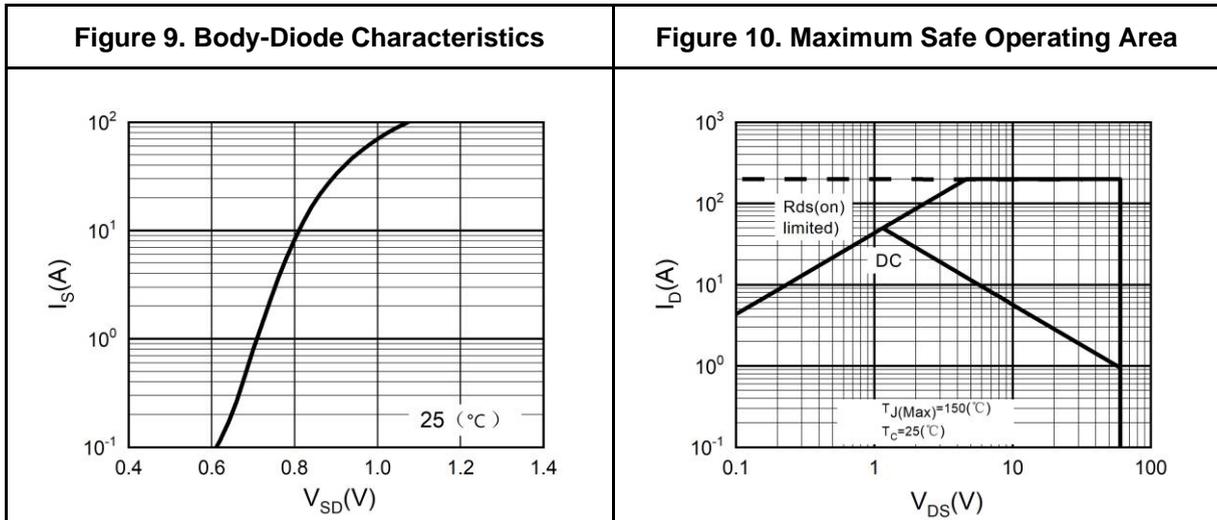
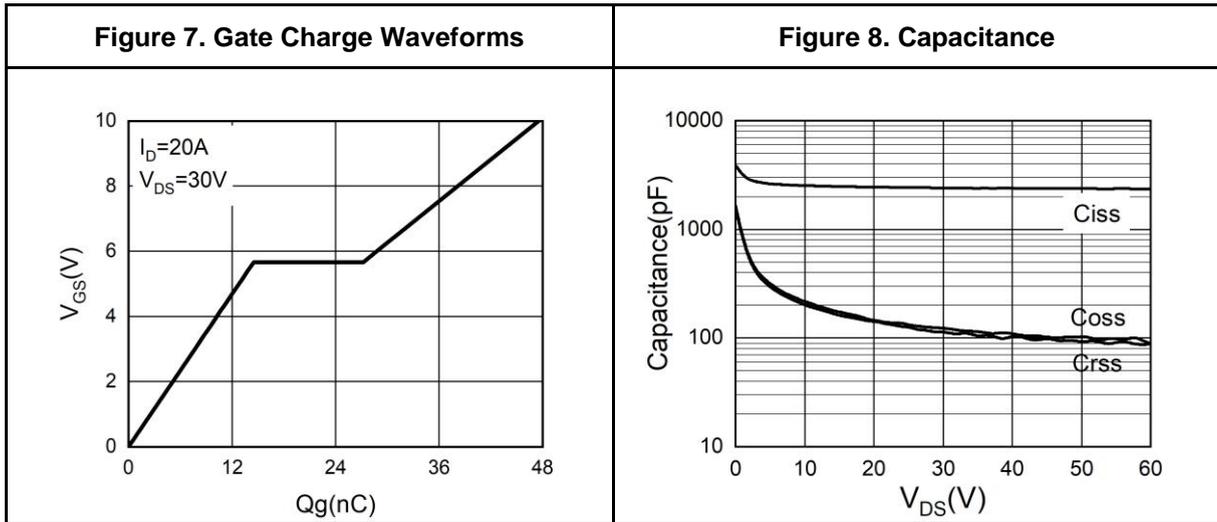
# 60V N-Channel Trench Power MOSFET

## Typical Electrical And Thermal Characteristics (Curves)



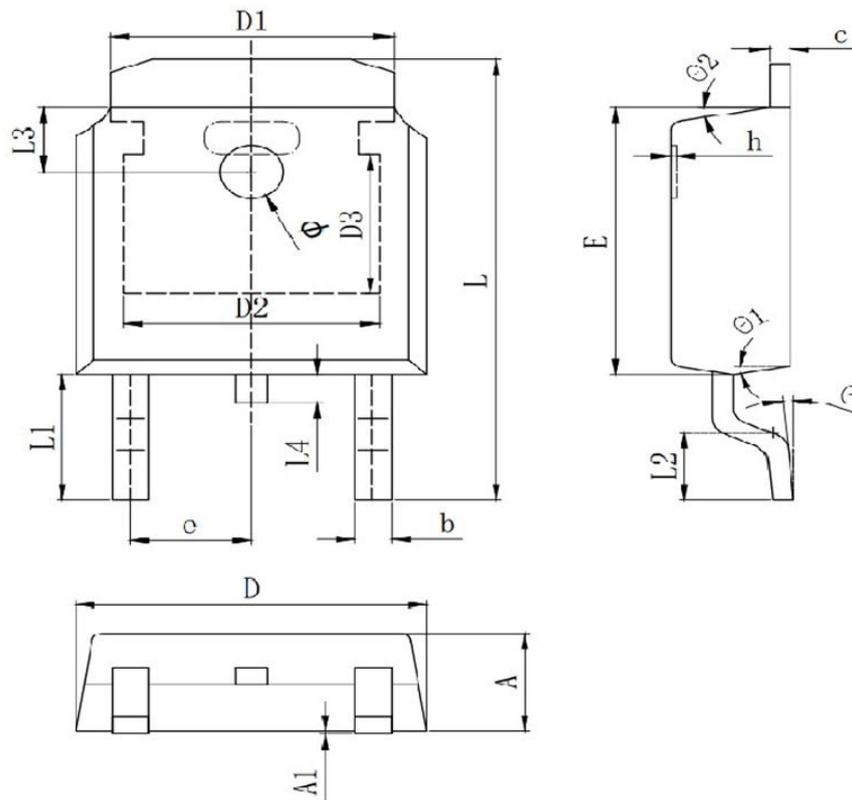


Typical Electrical And Thermal Characteristics (Curves)





TO-252 Package Information



Symbol	Dimensions In Millimeters		
	Min.	Typ.	Max.
A	2.200	2.300	2.400
A1	0.000		0.127
b	0.640	0.690	0.740
c(电镀后)	0.460	0.520	0.580
D	6.500	6.600	6.700
D1	5.334 REF		
D2	4.826 REF		
D3	3.166 REF		
E	6.000	6.100	6.200
e	2.286 TYP		
h	0.000	0.100	0.200
L	9.900	10.100	10.300
L1	2.888 REF		
L2	1.400	1.550	1.700
L3	1.600 REF		
L4	0.600	0.800	1.000
Φ	1.100	1.200	1.300
θ	0°		8°
θ1	9° TYP		
θ2	9° TYP		



## Attention

This product described in this document can not be used in life support devices or systems, aircraft's control systems, and other applications whose failure can be reasonably expected to result in serious physical and/or material damage, apart from that when an application agreement is signed between customer and Wuxi Shangjia Semiconductor.

The performances and characteristics of this product in the independent testing state are displayed in this document. Wuxi Shangjia Semiconductor can't guarantee of the performances and characteristics of this described product that mounted in the customer's products or equipments as same as that in the independent testing state. So the customer should evaluate and test devices mounted in the customer's products or equipments.

Wuxi Shangjia Semiconductor reserves the right to improve the designs, functions and reliability of this product and modify any and all information described in this document without notice customer, apart from that when an notice agreement is signed between customer and Wuxi Shangjia Semiconductor.

The information given in this document shall in no event be regarded as a guarantee of conditions or characteristics. With respect to any examples or hints given herein, any typical values stated herein and/or any information regarding the application of the device, Wuxi Shangjia Semiconductor hereby disclaims any and all warranties and liabilities of any kind, including without limitation, warranties of non-infringement of intellectual property rights of any third party.